

2010 Top 20 Semiconductor Companies Ranking

Company Profile

Industry: Semiconductor Foundry Services

Date Incorporated: May, 1980

About UMC: UMC (NYSE: UMC, TWSE: 2303) is a leading global semiconductor foundry that provides advanced technology and manufacturing services for applications spanning every major sector of the IC industry. UMC's customer-driven foundry solutions allow chip designers to leverage the strength of the company's leading-edge processes, which include production proven 65nm, 45/40nm, mixed signal/RFCMOS, and a wide range of specialty technologies. Production is supported through 10 wafer manufacturing facilities that include two advanced 300mm fabs; Fab12A in Taiwan and Singapore-based Fab12i are both in volume production for a variety of customer products. The company employs over 13,000 people worldwide and has offices in Taiwan, Japan, Singapore, Europe, and the United States. UMC can be found on the web at <http://www.umc.com>.

2010 ratings	2009 ratings	Company	2010 revenue	YOY change (%)
1	1	TSMC	US\$13.3B	48
2	2	UMC	US\$3.9B	41
3	3	GlobalFoundries	US\$3.5B	219
4	4	SMIC	US\$1.5B	45
5	5	Tower Jazz	US\$510M	70
6	6	VISC	US\$508M	33
7	7	Dongbu	US\$495M	25
8	8	IBM	US\$430M	28
9	9	MagnaChip	US\$420M	60
10	10	Samsung	US\$400M	38

Source: IC Insights

Chronology

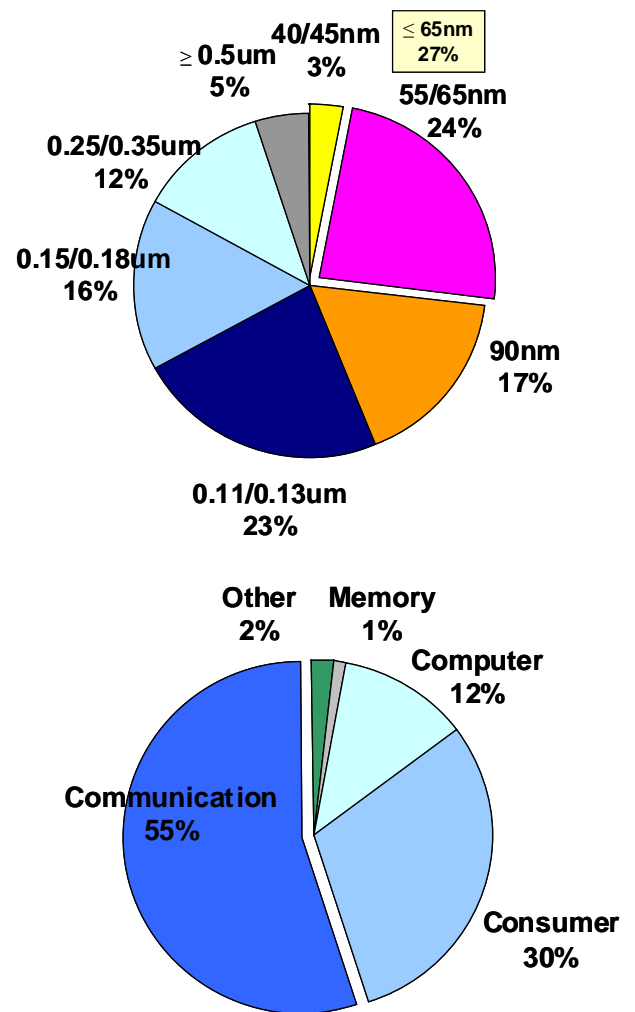
1980	May	UMC established
1985	Jul	Becomes the first IC company to list on the Taiwan Stock Exchange
1995	Jul	Begins transformation into a pure-play foundry
	Jul –Sep	Establishes three joint venture foundries; USC, UICC, USiC
1998	Apr	Acquires Holtek Semiconductor
	Dec	Acquires Nippon Steel Semiconductor Corp.; renamed UMCJ in 2001
1999	Nov	Begins construction of a 300mm fab in Taiwan's Tainan Science Park, Fab 12A
2000	Jan	Consolidates five companies: UMC, USC, UTEK, USI, and UICC
	May	Produces foundry industry's first 0.13um ICs
	Sep	Debuts on the New York Stock Exchange
	Dec	Announces plan to establish advanced 300mm foundry in Singapore (UMCi)
2003	Mar	Delivers foundry's first customer ICs built on 90nm
2004	May	90nm full qualification and volume production
	Jul	Completes acquisition of SiS Microelectronics Corp.
	Dec	Fully acquires its subsidiary UMCi; renames UMC Fab 12i
2005	Jun	Delivered the foundry industry's first 65nm customer products
	Aug	Achieves record milestone of over 100,000 90nm wafer shipments
2006	Jun	Becomes first IC company to achieve QC080000 IECO HSPM qualification for all fabs
	Nov	Produces working 45nm ICs
2007	Jan	Expands advanced technology complex in Tainan Science Park
2008	Sep	Named as a Global Index Component for Dow Jones Sustainability Indexes
2009	Apr	Delivers 40-nanometer customer ICs
	Dec	Fully acquires Japan subsidiary UMCJ
2010	May	Celebrates 30th anniversary
	Dec.	Begins production at 300mm Fab 12A Phase 3



Financial Highlights

	2010	2009	2008	2007	2006
Income Statement (NT\$ billion)					
Net Operating Revenue	120.4	88.6	92.5	106.8	104.1
Gross Profit	36.1	15.9	15.6	22.5	20.7
Operating Income(Loss)	22.6	3.3	2.3	6.8	6.1
Net Income(Loss)	23.9	3.9	(22.3)	17.0	32.6
Balance Sheet (NT\$ billion)					
Total Assets	263.4	251.9	208.0	290.8	355.2
Cash and Cash equ.	32.9	52.8	36.1	37.5	83.4
Total Liabilities	44.0	38.3	23.3	54.3	64.0
Long-term Liabilities	0.9	0.8	8.1	7.6	30.4
Stockholders' Equity	219.3	213.6	184.7	236.5	291.2
Cash Flow Statement (NT\$ billion)					
Cash Flow from Operations	55.4	32.5	44.8	46.8	46.0
Cash Flow from Investing	(60.3)	(20.6)	(12.3)	(23.7)	(15.9)
Cash Flow from Financing	(14.7)	5.0	(34.0)	(68.9)	(43.3)
Net Cash Flow	(19.9)	16.7	(1.3)	(45.9)	(13.2)
Free Cash Flow	(2.9)	14.9	33.4	18.7	14.8
Financial Analysis (%)					
Debt Ratio	16.7	15.2	11.2	18.7	18.0
Current Ratio	177.9	259.5	477.8	158.2	394.0
Quick Ratio	146.2	230.6	401.6	130.3	351.8

2010 Revenue Breakdown



UMC Fab12A 300mm Complex



LAST UPDATED: Feb., 2011

Research Coverage

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